2013 IEEE International Interconnect Technology Conference
June 13-15, 2013 | Kyoto, Japan

Sponsored by: IEEE EDS
Technically co-sponsored by: JSAP
http://www.semiconportal.com/IITC2013/

Paper Submission Due is extended until 5pm, January 28, 2013 (PST)

CALL FOR PAPERS

The 16th annual IEEE International Interconnect Technology Conference (IITC) and exhibition, sponsored by IEEE Electron Devices Society and technically co-sponsored by the Japan Society of Applied Physics (JSAP), has announced a Call for Papers for work describing innovative developments in the critically important field of interconnections for electronic systems. The conference seeks papers on all aspects of interconnects for device, circuit board and system-level applications. The deadline for submission of paper abstracts is extended until 5pm, January 28, 2013 (PST).

IITC 2013 will be held June 13-15 in Kyoto, Japan. It will be held adjacent to the IEEE VLSI Symposium, which is also being held in Kyoto. The conference attracts professionals from industry, academia, and national laboratories in semiconductor processing, interconnect design, and equipment development.

The conference topics include both fundamental and applied research, as well as issues related to introduction into manufacturing. **Subjects of interest** include **all aspects of Interconnects**: *Materials and Unit Processes, Process Integration, Characterization, Reliability, Chip-Package Interaction (CPI), 3D Integration and TSV Technology, Novel Systems and Packaging, Novel Materials and Concepts, Back-End Memories, beyond CMOS, and MEMS as well as the Specific Interest Areas listed below.*

This year, the Organizing Committee is explicitly soliciting contributions in the following specific interest areas: optical interconnects, technology-design interactions, patterning, beyond copper-low k interconnects, back-end embedded memories, and 3D integration.

CONFERENCE FORMAT

Technical Papers: Submissions addressing all aspects of interconnect technology will be rigorously reviewed.
・Regular papers, with 3-page abstracts, will be selected for either oral or poster presentation. For accepted papers, these 3-page abstracts will be published in the IEEE conference proceedings without the opportunity for further change.
・Papers with 2-page abstracts, e.g., from Young Engineers and Students, will undergo the same review process but will be accepted only for poster presentation. Also, the 2-page abstracts will be published in the IEEE conference proceedings.
・Oral presentations will be 20 minutes in length followed by a 5-minute time slot for questions. Poster authors are requested to be at their presentations for a 2-hour period on the day of their poster display.

Exhibits/Seminars: New products, processes, analytical methods and materials will be exhibited at the conference. Supplier seminars will be held on the 1st or 2nd evenings of the conference.

For further details about paper submissions, supplier seminar opportunities or other aspects of the conference, please contact iitc_2013@semiconportal.com